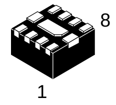
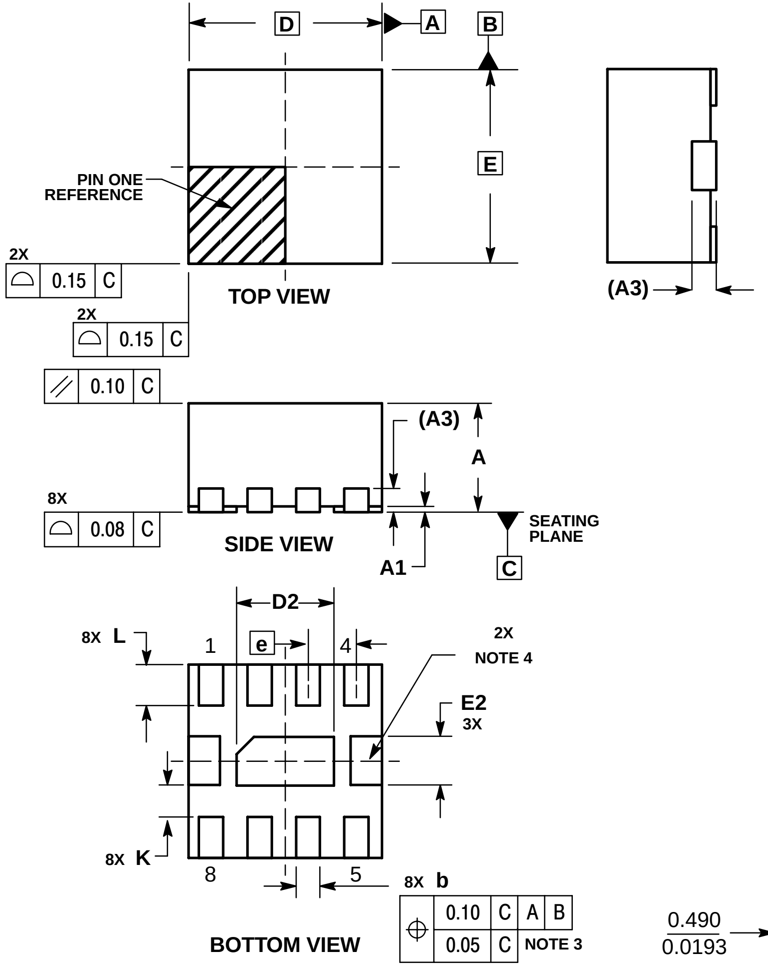


SCALE 4:1

DFN8
CASE 506AK−01
ISSUE C

DATE 30 SEP 2005

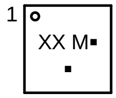


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
4. EXPOSED PADS CONNECTED TO DIE FLAG. USED AS TEST CONTACTS.

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	1.60 BSC	
D2	0.70	0.90
E	1.60 BSC	
E2	0.30	0.50
e	0.40 BSC	
K	0.20	−−−
L	0.20	0.40

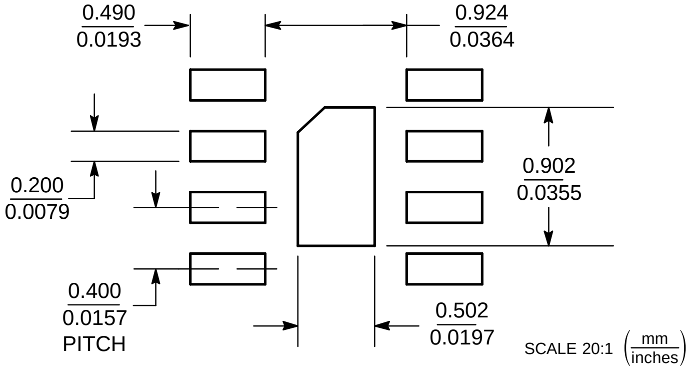
GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**DFN8 1.6*1.6 MM 0.4 MM LEAD PITCH**	**PAGE 1 OF 2**

ON Semiconductor®	DOCUMENT NUMBER: 98AON20130D PAGE 2 OF 2

ISSUE	REVISION	DATE
O	RELEASE FOR PRODUCTION. REQ. BY A. TAM.	30 DEC 2004
A	CHANGED MARKING. REQ. BY A. TAM	10 FEB 2005
B	ADDED SOLDERING FOOTPRINT. REQ. BY A. TAM.	29 AUG 2005
C	FIXED BOTTOM VIEW LABELING. REQ. BY P. CELAYA.	30 SEP 2005

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